

UG333: Class 4 Isolated Evaluation Board for the Si34061

The Si34061 isolated Flyback topology based evaluation board is a reference design for a power supply in a Power over Ethernet (PoE) Powered Device (PD) application.

This Si34061-ISO-FB EVB maximum output level is Class 4 power (η x 30 W).

The Si34061-ISO-FB EVB is shown below. The Si34061 IC integrates an IEEE 802.03at compatible PoE+ interface as well as a current control based dc/dc converter.

The Si34061 PD integrates two diode bridges, which can be used up to 200 mA input current, detection circuit, classification circuit, dc/dc switch, hot-swap switch, TVS overvoltage protection, dynamic soft-start circuit, cycle-by-cycle current limit, syncrhonous gate driver, bias winding option, maintain power signature (MPS), thermal shutdown and inrush current protection.

Beyond this, to improve thermal and power performance Si34061 integrates a driver for an external hot swap switch, as well as a driver for a primary dc/dc switch.

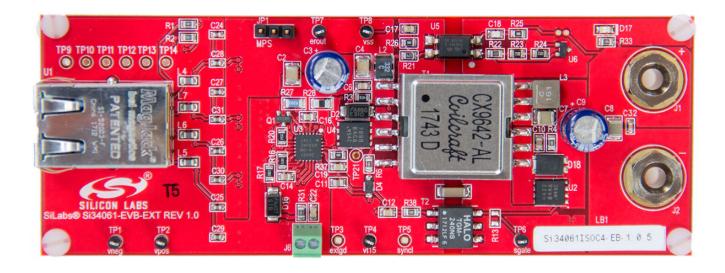
To improve efficiency, the Si34061 can be driven from an auxiliary bias winding.

Besides a PoE input, the Si34061 is capable of running from an external wall adapter with a minimum voltage of 12 $\rm V$.

The switching frequency of the converter is tunable by an external resistor.

KEY FEATURES

- · IEEE 802.03at Compatible
- · High Efficiency
- · High Integration
- · Optional MPS Function
- · External Primary Switch Driver
- · External HSSW Driver
- · Auxiliary Bias Winding Support
- Wall Adapter Support from 12 V
- · Synchronous Gate Driver
- · High Flexibility
- · Transient Overvoltage Protection
- · Thermal Shutdown Protection
- 5x5 mm 24-pin QFN



1. Kit Description

The Si34061-ISO-FB EVB Flyback topology based evaluation board is a reference design for power supplies in Power over Ethernet (PoE+) Powered Device (PD) applications. The Si34061 device is described more completely in the data sheet and application notes. This document describes the evaluation board.

The Si34061-ISO-FB-C4 EVB board is shown on the cover page. The schematic is shown in Figure 2.3 Si34061-Isolated Flyback EVB Schematic: 5 V, Class 4 PD on page 4, and the layout is in 15. Board Layout. The dc output is at connectors J1(+) and J2(–).

Boards are shipped configured to produce 5 V output voltage but can be configured for different output voltages, such as 3.3 or 12 V, by changing resistor R23 and a few other components. Refer to "AN1130: Using the Si3406/Si34061/Si34062 PoE+ and Si3404 PoE PD Controller in Isolated and Non-Isolated Designs" for more information. The preconfigured Class 4 signature can also be modified, which is described as well in AN1130.

The Si34061 includes integrated diode bridge for both CT and SP connection. The integrated diode bridge can be used up to 200 mA input current. Above 200 mA input current the external diode bridge is required. This board is set up with external Schottky diode bridges.

The external diode bridge can be of a silicon type as well; in this case, the CT/SP pins should be connected.

To compensate the reverse leakage of the Schottky type diode bridges at high temperature, the recommended detection resistor should be adjusted to the values listed in the following table:

Table 1.1. Recommended Detection Resistor Values

External Diode Bridge	R _{DET}
Silicon Type	24.3 kΩ
Schottky Type	24.9 kΩ

2. Getting Started: Powering Up the Si34061-ISO-FB EVB

Ethernet data and power are applied to the board through the RJ45 connector (U1). The board itself has no Ethernet data transmission functionality, but, as a convenience, the Ethernet transformer secondary-side data is brought out to test points.

The design can be used in Gigabit (10/100/1000) systems as well by using PoE RJ45 Magjack, such as type L8BE-1G1T-BFH from Bel Fuse.

Power may be applied in the following ways:

- Using an IEEE 802.3-2015-compliant, PoE-capable PSE, such as Trendnet TPE-1020WS
- · Using a laboratory power supply unit (PSU):
 - Connecting a dc source between blue/white-blue and brown/white-brown of the Ethernet cable (either polarity), (End-span) as shown below:

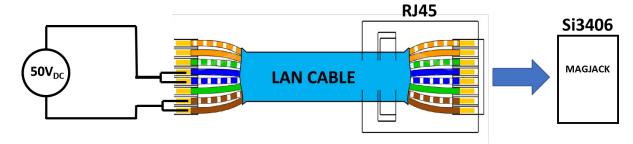


Figure 2.1. Endspan Connection using Laboratory Power Supply

• Connecting a dc source between green/white-green and orange/white-orange of the Ethernet cable (either polarity), (Mid-span) as shown below:

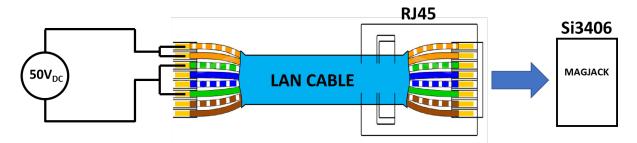


Figure 2.2. Midspan Connection using Laboratory Power Supply

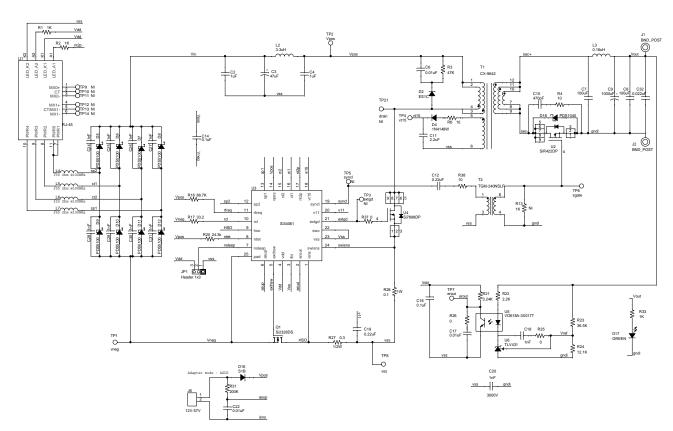


Figure 2.3. Si34061-Isolated Flyback EVB Schematic: 5 V, Class 4 PD

3. Overall EVB Efficiency

The overall efficiency measurement data of the Si34061-ISO-FB EVB board is shown below. The input voltage is 50 V, output voltage is 5 V.

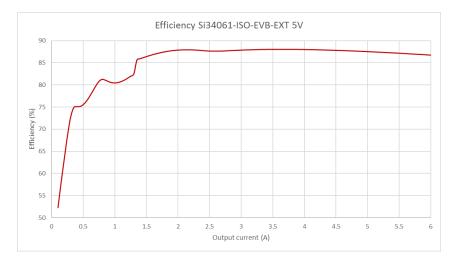


Figure 3.1. Si34061-Isolated Flyback Class 4 EVB Overall Efficiency: 50 V Input, 5 V Output

Note: The chart shows overall EVB efficiency. The voltage drop on the external Schottky diode bridge is included.

4. SIFOS PoE Compatibility Test Results

The Si34061-ISO-FB EVB board has been successfully tested with PDA-300 Powered Device Analyzer from SIFOS Technologies. The PDA-300 Powered Device Analyzer is a single-box comprehensive solution for testing IEEE 802.3at PoE Powered Devices (PDs).



Figure 4.1. Si34061-Isolated Flyback C4 PD SIFOS PoE Compatibility Test Results

5. Feedback Loop Phase and Gain Measurement Results (Bode Plots)

The Si34061 device integrates a current mode controlled switching mode power supply controller circuit. Therefore, the application is a closed-loop system. To guarantee a stable output voltage of a power supply and to reduce the influence of input supply voltage variations and load changes on the output voltage, the feedback loop should be stable.

To verify the stability of the loop, the loop gain and loop phase shift has been measured.

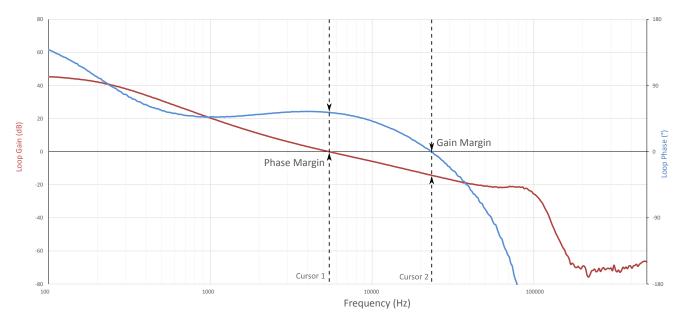


Figure 5.1. Si34061-ISO-FB EVB Measured Loop-Gain and Phase Shift

Table 5.1. Measured Loop Gain and Phase Shift

	Frequency	Gain	Phase
Cursor 1 (Phase Margin)	5.4 kHz	0 dB	54°
Cursor 2 (Gain Margin)	23 kHz	–14 dB	0 °

6. Step Load Transient Measurement Results

The Si34061-ISO-FB EVB board's output has been tested with a step load function to verify the converters output dynamic response.

Step Load: From 1 A to 5 A Output Current

Step Load: From 5 A to 1 A Output Current



Figure 6.1. Si34061-ISO-FB EVB PD Output Step Load Transient Test

7. Output Voltage Ripple

The Si34061-ISO-FB C4 output voltage ripple has been measured in both no load and heavy load conditions.

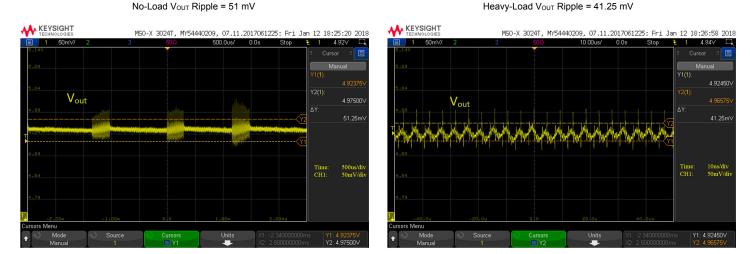


Figure 7.1. Si34061-Isolated Flyback C4 EVB Output Voltage Ripple No Load (Left) and Heavy Load (Right) Conditions

8. Soft Start Protection

The Si34061 device has an integrated dynamic soft-start protection mechanism to avoid stressing the components by the sudden current or voltage changes associated with the initial charging of the output capacitors.



Figure 8.1. Si34061 Isolated Flyback C4 EVB Input Current and Output Voltage Soft-Start at Low Load (Left) and Heavy Load (Right) Conditions

9. Output Short Protection

The Si34061 device has an integrated output short protection mechanism, which protects the IC itself and the surrounding external components from overheating in the case of electrical short on the output.



Figure 9.1. Si34061-Isolated Flyback C4 EVB Output Voltage and Input Current when Output is Shorted

10. Pulse Skipping at No-Load Condition

The Si34061 device has an integrated pulse skipping mechanism to ensure ultra-low power consumption at no load condition.

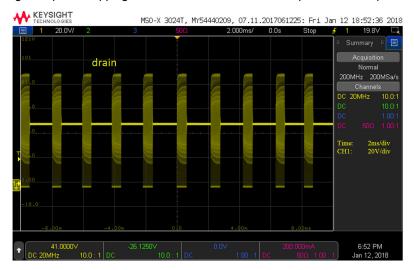


Figure 10.1. Si34061 Pulse Skipping at No-load Condition: SWO Waveform

11. Adjustable EVB Current Limit

For additional safety, the Si34061 has an adjustable EVB current limit feature. The EVB current limit through the ISNS pin measures the voltage on R_{SENSE} . When V_{RSENSE} = -270 mV (referenced to Vss), the current limit circuit restarts the circuit to protect the application.

The EVB current limit for this Class 4 application can be calculated with the following formula:

$$R_{SFNSF} = 0.3\Omega$$

$$I_{LIMIT} = \frac{270mV}{0.3\Omega} = 900mA$$

Equation 1. EVB Current Limit

12. Tunable Switching Frequency

The switching frequency of the oscillator is selected by choosing an external resistor (R_{FREQ}) connected between the RFREQ and VPOS pins. The following figure will aid in choosing the R_{FREQ} value to achieve the desired switching frequency.

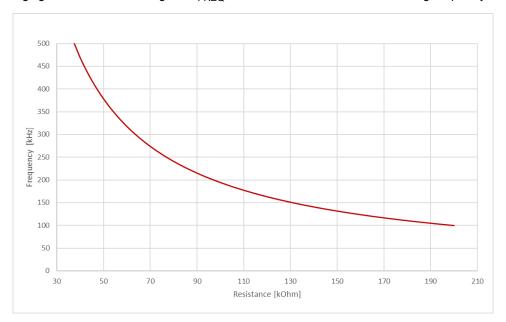


Figure 12.1. Switching Frequency vs R_{FREQ}

The selected switching frequency for this application is 220 kHz, which is achieved by setting the RFREQ resistor to 88.7 kΩ.

13. Synchronous Rectification

The Si34061 device has synchronous gate driver (SYNCL) to drive the rectifier MOSFET. At low-load the converter works in discontinuous current mode (DCM); at heavy load, the converter runs in continuous current mode (CCM). At low-load the SWO voltage waveform has a ringing waveform, which is typical for a DCM operation.

Low-load, DCM, sync-FET disabled, Non-Synchronous

Non-Synchronous

Synchronous

KEYSIGHT
TECHNOLOGIE

MSD.X 3024T, MY54440209, 07.11.2017061225: Thu Nov 23 18:21:56 2017

MSD.X 3024T, MY54440209, 07.11.2017061225: Thu Nov 23 18:33:12 2017

Acquisition
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Figure 13.1. DC-DC Switch Drain and SYNCL Voltage Waveforms at Discontinuous Current Mode (DCM) (Left) and in Continuous Current Mode (CCM) (Right)

The device operates in non-synchronous mode at light load (I_{IN} < 25 mA). As the input current increases, Si34061 automatically changes its switching operation from "Non-Synchronous" to "Synchronous". The dynamic operation adjustment maximizes overall power efficiency.

14. Maintain Power Signature

The Si34061 device integrates an MPS circuit which ensures connection with the PSE if the PD application current drops below PSE threshold level.

There are two modes of MPS operation:

- · Automatic mode MPS (consumption-based)
- · User mode MPS

Automatic Mode MPS (Consumptions Based):

If *nSLEEP* is low at startup, MPS generation depends on chip current consumption:

- MPS pulses are enabled below a certain level of total PD current consumption to ensure connection with the PSE
- · MPS pulses are disabled above a certain level of total PD current consumption not to degrade overall board efficiency



Figure 14.1. Automatic MPS Mode, nSLEEP is Low; MPS is Enabled when PD Consumption is Low; MPS is Disabled when PD Consumption is Higher

User Mode MPS:

If nSLEEP is high at startup, MPS generation depends on nSLEEP.

- if nSLEEP is high, MPS disabled (independently of the current consumption)
- if nSLEEP is low, MPS enabled (independently of the current consumption)



Figure 14.2. With nSLEEP High, MPS is Disabled (Left); with nSLEEP Low, MPS is Enabled (Right); MPS

Generation is Fully Controlled by the User

15. Board Layout

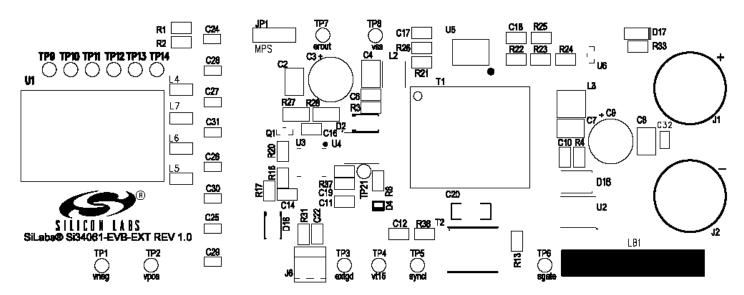


Figure 15.1. Top Silkscreen

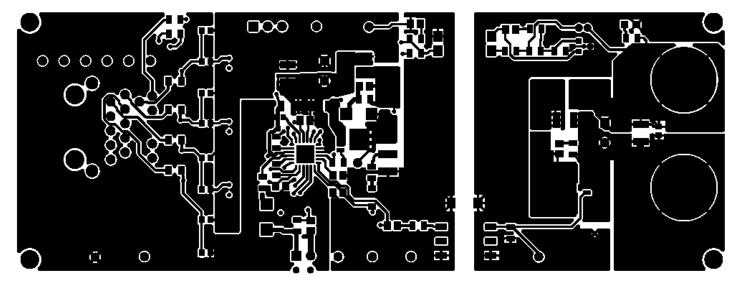
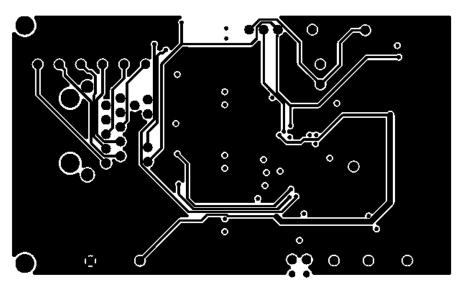


Figure 15.2. Top Layer



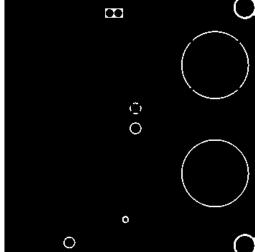
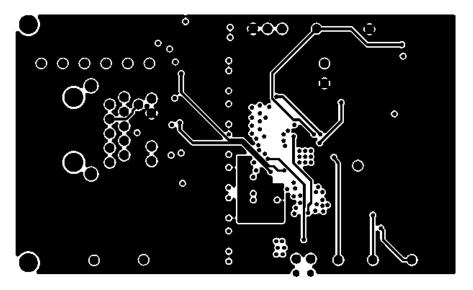


Figure 15.3. Internal 1 (Layer 2)



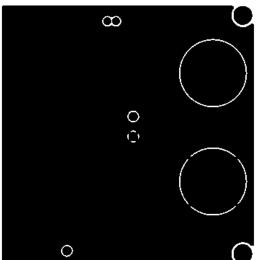
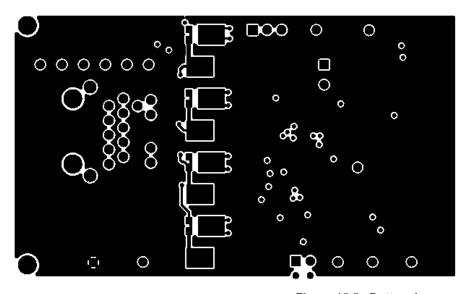


Figure 15.4. Internal 2 (Layer 3)



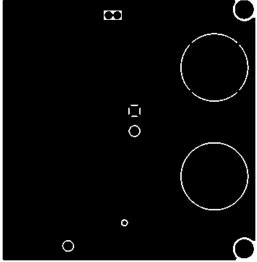


Figure 15.5. Bottom Layer

16. Bill of Materials

The following table is the BOM listing for the standard 5 V output evaluation board with option PoE Class 4.

Table 16.1. Si34061-ISOC4 EVB Bill of Materials

Qty	Value	Ref	Rating	Volt- age	Tol	Туре	PCB Footprint	Mfr Part Number	Mfr
2	1 μF	C2, C4		100 V	±10%	X7R	C1210	C1210X7R101-105K	Venkel
1	47 μF	C3		100 V	±20%	Alum_El ec	C3.5X8MM-RAD	ECA2AM470	Panasonic
3	0.01 μF	C6, C17, C22		100 V	±10%	X7R	C0805	C0805X7R101-103K	Venkel
2	100 μF	C7, C8		6.3 V	±10%	X5R	C1210	C1210X5R6R3-107K	Venkel
1	1000 μF	C9		6.3 V	±20%	Alum_El ec	C3.5X8MM-RAD	ECA0JM102	Panasonic
1	470 pF	C10		50 V	±10%	X7R	C0805	C0805X7R500-471K	Venkel
1	2.2 µF	C11		25 V	±20%	X7R	C0805	C0805X7R250-225M	Venkel
2	0.22 μF	C12, C19		10 V	±10%	X7R	C0805	C0805X7R100-224K	Venkel
1	0.1 μF	C14		100 V	±10%	X7R	C0805	C0805X7R101-104K	Venkel
1	0.1 μF	C16		16 V	±20%	X7R	C0805	C0805X7R160-104M	Venkel
1	1 nF	C18		50 V	±1%	C0G	C0805	C0805C0G500-102F	Venkel
1	1 nF	C20		3000 V	±10%	X7R	C1808	C1808X7R302-102K	Venkel
8	1 nF	C24, C25, C26, C27, C28, C29, C30, C31		100 V	±10%	X7R	C0603	C0603X7R101-102K	Venkel
1	0.022 µF	C32		50 V	±20%	X7R	C0603	C1608X7R1H223M	TDK Corp.
1	ES1C	D2	1.0 A	150 V		Fast	DO-214AC	ES1C	Diodes Inc.
1	1N4148 W	D4	2 A	100 V		Fast	SOD123	1N4148W	Diodes Inc
8	PDS5100	D5, D6, D7, D8, D9, D10, D11, D12	5 A	100 V		Schottky	POWERDI-5	PDS5100H-13	Diodes Inc.
1	S1B	D16	1.0 A	100 V		Single	DO-214AC	S1B	Fairchild
1	GREEN	D17	30 mA	2.2 V		SMT	LED-0805-K	LTST-C170GKT	LITE_ON Inc.
1	PDS1040	D18	10 A	40 V		Schottky	POWERDI-5	PDS1040-13	Diodes Inc.
1	Header 1x3	JP1				Header	CONN-1X3	TSW-103-07-G-S	Samtec
2	BND_PO ST	J1, J2	15 A			BANA- NA	BANANA-JACK	101	Abbatron HH Smith
1	CONN TRBLK 2	J6				TERM BLK	CON1X2-1725656	1725656	Phoenix Con- tact
1	3.3 µH	L2	1.5 A		±20%	Unshiel- ded	IND-8400	84332C	Murata

Qty	Value	Ref	Rating	Volt- age	Tol	Туре	PCB Footprint	Mfr Part Number	Mfr
1	0.16 μH	L3	16 A		±20%	Shiel- ded	IND- XAL5030-161ME	IND-XAL5030-161ME	Coilcraft
4	330 Ω	L4, L5, L6, L7	1500 mA			SMT	L0805	BLM21PG331SN1	MuRata
1	Si2328D S	Q1	1.5 A	100 V		N-CHNL	SOT23-GSD	Si2328DS	Vishay
3	1 kΩ	R1, R2, R33	1/10 W		±1%	Thick- Film	R0805	CR0805-10W-1001F	Venkel
1	47 kΩ	R3	1/10 W		±5%	Thick- Film	R0805	CR0805-10W-473J	Venkel
3	10 Ω	R4, R6, R38	1/10 W		±1%	Thick- Film	R0805	CR0805-10W-10R0F	Venkel
1	88.7 kΩ	R16	1/8 W		±1%	Thick- Film	R0805	CRCW080588K7FKEA	vishay
1	33.2 Ω	R17	1/8 W		±1%	Thick- Film	R0805	CRCW080533R2FKEA	vishay
1	24.3 kΩ	R20	1/8 W		±1%	Thick- Film	R0805	CRCW080524K3FKEA	vishay
1	3.24 kΩ	R21	1/8 W		±1%	Thick- Film	R0805	CRCW08053K24FKEA	Vishay
1	2.2 kΩ	R22	1/10 W		±5%	Thick- Film	R0805	CR0805-10W-222J	Venkel
1	36.5 kΩ	R23	1/10 W		±1%	Thick- Film	R0805	CR0805-10W-3652F	Venkel
1	12.1 kΩ	R24	1/10 W		±1%	Thick- Film	R0805	CR0805-10W-1212F	Venkel
3	0 Ω	R25, R26, R37	2 A			Thick- Film	R0805	CR0805-10W-000	Venkel
1	0.3 Ω	R27	1/2 W		±1%	Thick- Film	R1206	LRC-LR1206LF-01- R300-F	TT Electron- ics
1	0.1 Ω	R28	1 W		±1%	Thick- Film	R1206	ERJ-8BWFR100V	Panasonic
1	200 kΩ	R31	1/10 W		±1%	Thick- Film	R0805	CR0805-10W-2003F	Venkel
1	CX-9642	T1	25 W	37 V-57 V		PoE+		CX-9642	Coilcraft
1	TGM-240 NSLF	T2	1500 V				TGM-240NSLF	TGM-240NSLF	Halo
1	RJ-45	U1				Recep- tacle	RJ45-SI-52004	SI-52003-F	Bel
1	SiR422D P	U2	40 A	40 V		N-CHNL	POWER56	SiR422DP	Vishay
1	Si34061	U3		120 V		PD		Si34061	SiLabs
1	Si7898D P	U4	4.8 A	150 V		N-CHNL	POWER56	Si7898DP	Vishay

Qty	Value	Ref	Rating	Volt- age	Tol	Type	PCB Footprint	Mfr Part Number	Mfr
1	VO618A- 3X017T	U5					SO4N10.16P2.54- AKEC	VO618A-3X017T	Vishay
1	TLV431	U6				SHUNT	TLV431-DBZ	TLV431BCDBZR	TI
Not Installed Components									
1	1 kΩ	R13	1/10 W		±1%	Thick- Film	R0805	CR0805-10W-1001F	Venkel

17. Appendix—Si34061ISOC4 Design and Layout Checklist

Although the EVB design is pre-configured as a Class 4 PD with 5 V output, the schematics and layouts can easily be adapted to meet a wide variety of common output voltages and power levels.

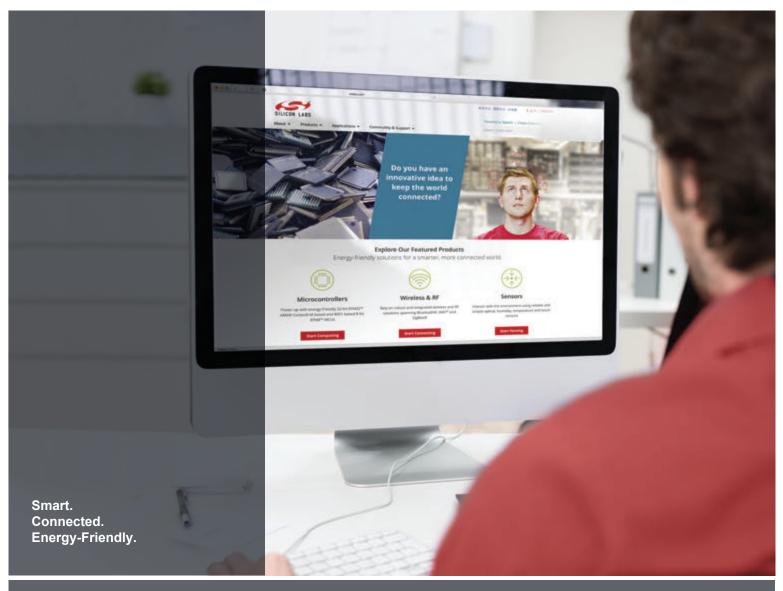
The complete EVB design databases for the standard 5 V/Class 4 configuration are located at www.silabs.com/PoE link. Silicon Labs strongly recommends using these EVB schematics and layout files as a starting point to ensure robust performance and avoid common mistakes in the schematic capture and PCB layout processes.

Below is a recommended design checklist that can assist in trouble-free development of robust PD designs.

Refer also to the Si34061 data sheet and AN1130 when using the following checklist.

- 1. Design Planning checklist:
 - a. Determine if your design requires an isolated or non-isolated topology. For more information, see AN1130.
 - b. Silicon Labs strongly recommends using the EVB schematics and layout files as a starting point as you begin integrating the Si34061ISOC4 into your system design process.
 - c. Determine your load's power requirements (i.e., VOUT and IOUT consumed by the PD, including the typical expected transient surge conditions). In general, to achieve the highest overall efficiency performance of the Si34061-isolated Flyback, choose the highest output voltage option used in your PD and then post regulate to the lower supply rails, if necessary.
 - d. Based on your required PD power level, select the appropriate class resistor RCLASS value by referring to AN1130.
- 2. General Design checklist:
 - a. ESD caps (C24–C31 in Figure 2.3 Si34061-Isolated Flyback EVB Schematic: 5 V, Class 4 PD on page 4) are strongly recommended for designs where system-level ESD (IEC6100-4-2) must provide >15 kV tolerance.
 - b. If your design uses an AUX supply, be sure to include a 3 Ω surge limiting resistor in series with the AUX supply for hot insertion. Refer to AN1130 when AUX supply is 48 V.
- 3. Layout Guidelines:
 - a. Make sure VNEG pin of the Si34061 is connected to the backside of the QFN package with an adequate thermal plane, as noted in the data sheet and AN1130.
 - b. Keep the trace length from SWO to VSS as short as possible. Make all of the power (high current) traces as short, direct, and thick as possible. It is a good practice on a standard PCB board to make the traces an absolute minimum of 15 mils (0.381 mm) per ampere.
 - c. Usually, one standard via handles 200 mA of current. If the trace needs to conduct a significant amount of current from one plane to the other, use multiple vias.
 - d. Keep the circular area of the loop from the Switcher FET output to the inductor or transformer and returning from the input filter capacitors (C2–C4) to VSS as small a diameter as possible. Also, minimize the circular area of the loop from the output of the inductor or transformer to the Schottky diode and returning through the first stage output filter capacitor back to the inductor or transformer as small as possible. If possible, keep the direction of current flow in these two loops the same.
 - e. Keep the high power traces as short as possible.
 - f. Keep the feedback and loop stability components as far from the transformer/inductor and noisy power traces as possible.
 - g. If the outputs have a ground plane or positive output plane, do not connect the high current carrying components and the filter capacitors through the plane. Connect them together, and then connect to the plane at a single point.

To help ensure first-pass success, contact our customer support by submitting a help ticket and uploading your schematics and layout files for review.





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